HSMP-389Y

RF Switching PIN Diodes In Surface Mount SOD-523 Package



Data Sheet

Description/Applications

The HSMP-389Y of Avago Technologies is a PIN Diode that optimized for switching applications where low resistance at low current and low capacitance are required. It is housed in a miniature low cost surface mount SOD-523 package. This miniature package is particularly useful in the application where board space is the major concern.

A SPICE model is not available for PIN diodes as SPICE does not provide for a key PIN diode characteristic — carrier lifetime.

Features

- Space saving SOD-523 package
- Switching
 - Low Capacitance
 - Low Resistance at Low Current
- Tape and Reel Options Available
- MSL 1 & Lead Free

Package Marking and Pin Connections



Note: Package marking provides orientation and identification

"F" = Device Code

?" = Month code indicates the month of manufacture

Table 1. Absolute Maximum Ratings $^{[1]}$ at Tc = +25°C

Symbol	Parameter	Unit	Max Rating
I _f	Forward Current (1 µs Pulse)	Amp	1
P _{IV}	Peak Inverse Voltage	٧	100
T _j	Junction Temperature	°C	150
T_{stg}	Storage Temperature	°C	-60 to 150
θjb	Thermal Resistance [2]	°C/W	150

Notes:

- 1. Operation in excess of any one of these conditions may result in permanent damage to the device.
- 2. Thermal Resistance is measured from junction to board using IR method.

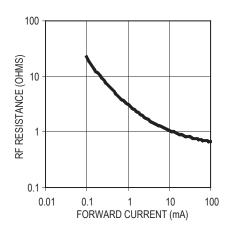
Table 2. Electrical Specifications at Tc = +25°C

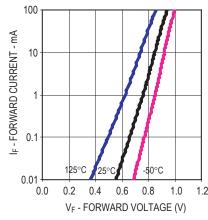
	Minimum Breakdown	Maximum Total	Maximum Total
	Voltage V _{BR} (V)	Resistance R _s (Ohm)	Capacitance CT (pF)
	100	2.5	0.30
Test Conditions	VR = VBR	I _F = 5 mA	$V_R = 5V$
	Measure IR ≤ 10∝A	f = 100 MHz	f = 1MHz

Table 3. Typical Parameters at Tc = +25°C

	Series Resistance Rs (Ohm)	Carrier Lifetime (ns)	Total Capacitance CT (pF)
	3.8	200	0.20
Test Conditions	I _F = 1 mA f = 100 MHz	$I_F = 10 \text{mA}$ $I_R = 6 \text{mA}$	$V_R = 5 V$ f = 1MHz

Typical Performance Curves at Tc = +25°C





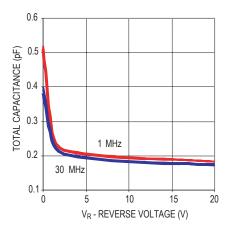
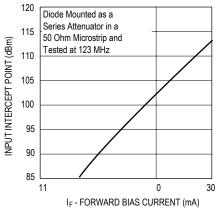


Figure 1. RF Resistance vs. Forward Bias Current

Figure 2. Forward Current vs. Forward Voltage

Figure 3. RF Capacitance vs. Reverse Bias



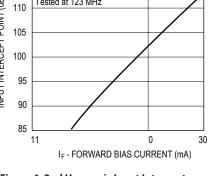


Figure 4. 2nd Harmonic Input Intercept **Point vs. Forward Bias Current**

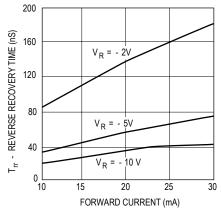
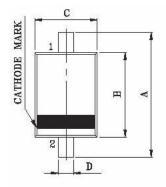
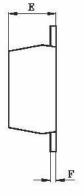


Figure 5. Typical Reverse Recovery Time vs. Reverse Voltage

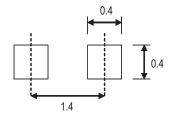
Package Outline and Dimension





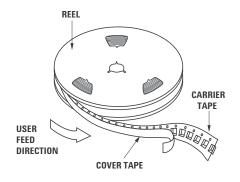
DIM	MILLIMETERS	
A	$1.60 {\pm} 0.10$	
В	1.20±0.10	
C	0.80±0.10	
D	0.30 ± 0.05	
E	0.60±0.10	
F	0.13±0.05	

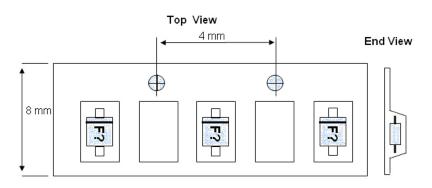
PCB Footprint



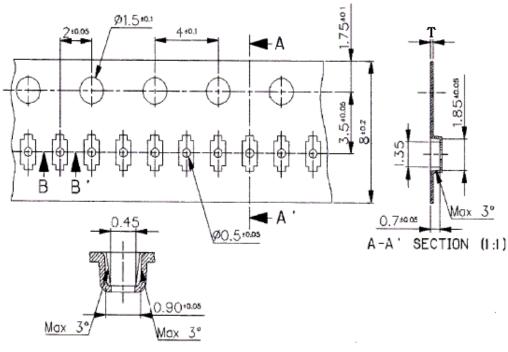
Unit: mm

Device Orientation





Tape Dimensions



B-B' SECTION (3:1)

Specification < Unit: mm >

hole pitch : 50 Pitch Tolerance : 200 ± 0.3

General Tolerance: ± 0.1

Surface resistance : 104 ~ 108 Ω

Part Number Ordering Information

Part number	No. of Units	Container
HSMP-389Y-BLKG	100	Anti-static bag
HSMP-389Y-TR1G	3000	7" reel

